Close Brothers Seydler Bank AG

Small and Mid Cap Conference 2011

Disclaimer

This presentation contains forward-looking statements relating to the business, financial performance and earnings of SUSS MicroTec AG and its subsidiaries and associates. Forward-looking statements are based on current plans, estimates, projections and expectations and are therefore subject to risks and uncertainties, most of which are difficult to estimate and which in general are beyond the control of SUSS MicroTec AG. Consequently, actual developments as well as actual earnings and performance may differ materially from those which are explicitly or implicitly assumed in the forward-looking statements. SUSS MicroTec AG does not intend or accept any obligation to publish updates of these forward-looking statements.

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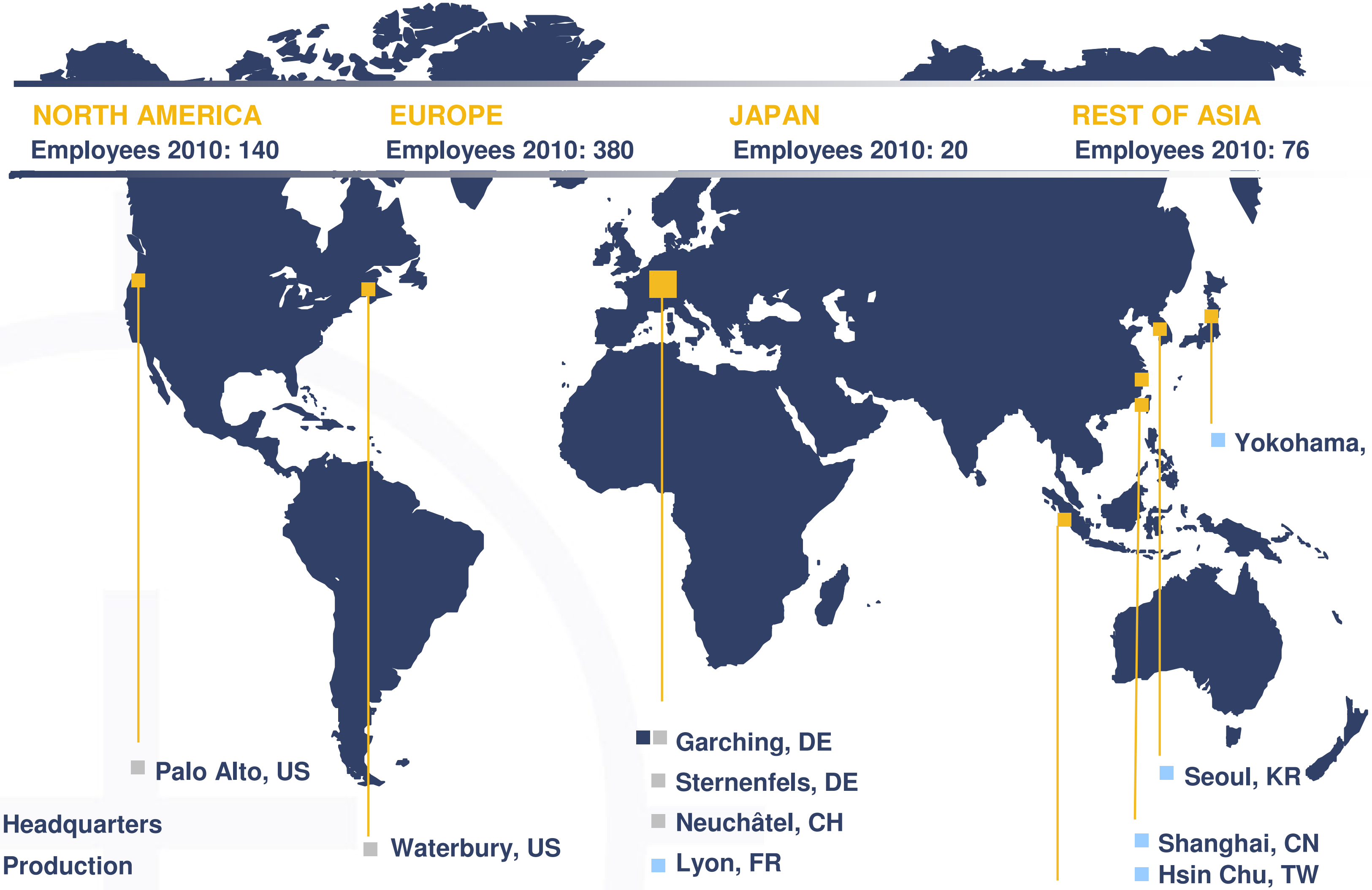
SUSS MicroTec Spotlight

- SUSS MicroTec: A global equipment leader in semiconductors
- Our equipment and process solutions create the micro structures that build and connect micro electronic devices
- We are focused on high growth market segments:

  Semiconductors, MEMS, LEDs

- 2010 order entry app. 190 million €
- 2010 guidance:
  - Sales 140 million €
  - EBIT range 11 – 13 million €
- More than 8,000 systems installed worldwide

SUSS MicroTec – a Global Player



NORTH AMERICA
Employees 2010: 140

EUROPE
Employees 2010: 380

JAPAN
Employees 2010: 20

REST OF ASIA
Employees 2010: 76

▨ Palo Alto, US

▨ Waterbury, US

■▨ Garching, DE
▨ Sternenfels, DE
▨ Neuchâtel, CH
□ Lyon, FR
□ Coventry, UK

□ Yokohama, JP

□ Seoul, KR
□ Shanghai, CN
□ Hsin Chu, TW
□ Singapore, SG

■ Headquarters
▨ Production
□ Sales

Major Milestones

- Explosive growth in order entry
- Acquisition of HamaTech APE
- Divestment of the loss making Test Systems division
- Relocation of the Substrate Bonder division from Waterbury, USA to Sternenfels, Germany
- Reduction of development and manufacturing sites from existing four in January 2010 to two highly efficient sites in Germany in 2011

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SUSS MicroTec In The Value Chain

Equipment Supplier

SUSS MicroTec

ICs & Components

End Products

End User

Research Institutes

imec

Fraunhofer IZM

工業技術研究院
Industrial Technology Research Institute

Infineon technologies

ASE INC. KAOHSIUNG

SPIL

SAMSUNG

FUJITSU

STATS

IBM

EPCOS

ANALOG DEVICES

TEXAS INSTRUMENTS

Amkor Technology

NOKIA Connecting People

SONY

SIEMENS

MOTOROLA

BOSCH

PHILIPS

SAMSUNG

OSRAM Opto Semiconductors

Mega Trends Driving our Key Markets

Computing

Communication

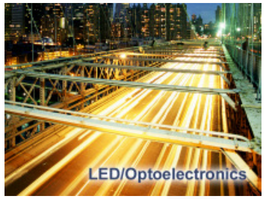
Entertainment

Transportation

Electronics

Sensors

Energy Efficiency



Solid State Lighting

Key Markets

Semiconductors
Front End
Back End

MEMS

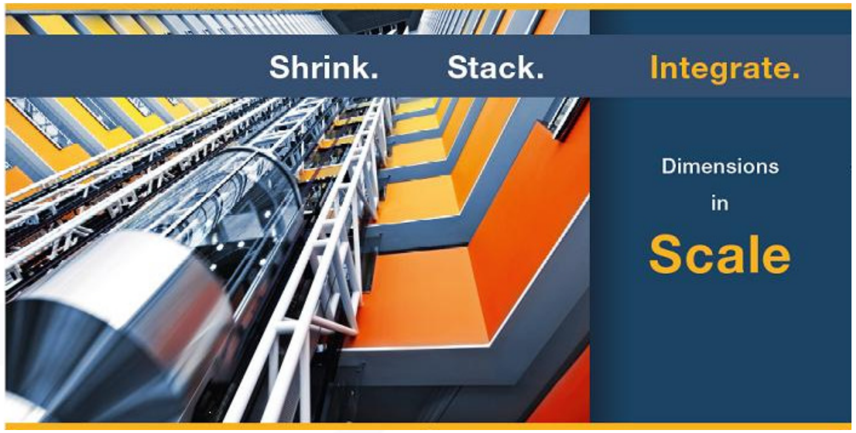
LED

Enabling Semiconductor Trends

- SUSS MicroTec drives and enables the fundamental challenges of the semiconductor Industry:

Shrinking – Stacking – Integrating

- The SUSS MicroTec family of products provides equipment and process solutions for 2-dimensional and 3-dimensional scaling



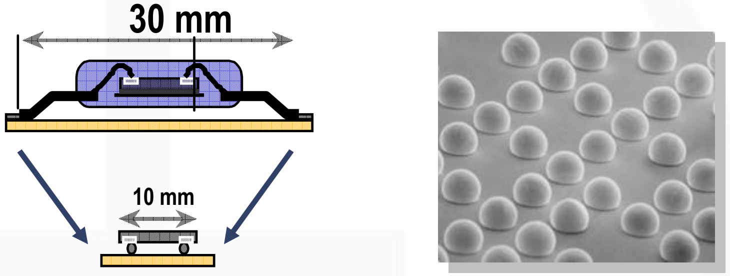
Semiconductors

- SUSS MicroTec offers solutions for performance and yield critical steps in semiconductor manufacturing
- Front End: Mask Cleaning
- Back End: Advanced Packaging
  3D Integration

Mask Cleaning

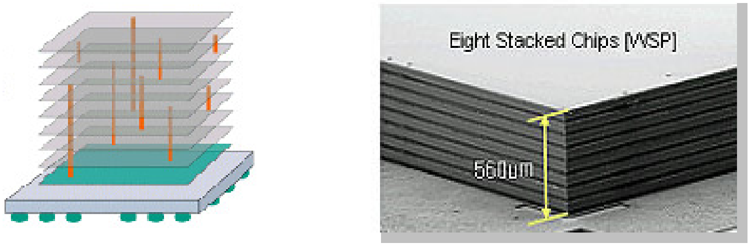
Maintains mask integrity of 193i sub 22nm, EUVL and NIL lithography

Advanced Packaging



Micro-bumping replaces wire-bonding for high-end integrated circuits

3D Integration



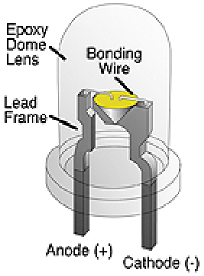
Stacking chips allows for higher device complexity

MEMS and LED

MEMS

- Micromechanical devices with electrical functions
- Micro Electro Mechanical Systems are found in a wide application range from automotive over industrial process control sensors to consumer products

LED

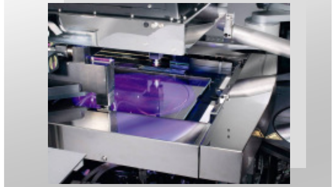
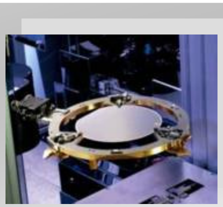


- Ultra High Brightness Light Emitting Diodes (UHB LED) for solid state lighting
- UHB LEDs drive rapidly growing LED markets like automotive, consumer electronics and lighting applications

- For MEMS and LED production SUSS MicroTec offers a comprehensive suite of products:

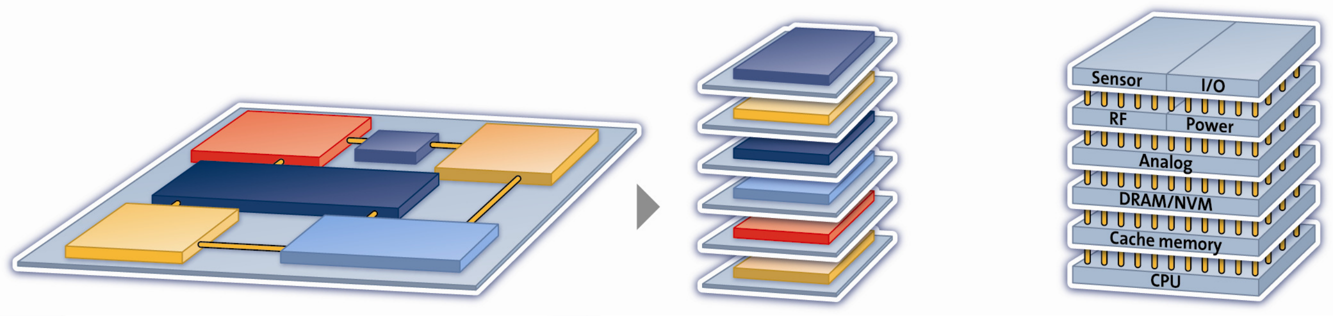
  Mask Aligners – Coaters / Developers – Wafer Bonders

Products and Process Solutions

Products	 Mask Track	 Mask Aligner	 Coater/ Developer	 Wafer Bonder
	Front-end	Back-end		
Process Steps	Photomask Cleaning	Alignment Exposure Nano Imprinting	Coating Developing	Bond Alignment Permanent Bonding Temporary Bonding
Market Share	~ 80%	~ 50%	~ 40 – 50%	~ 30%

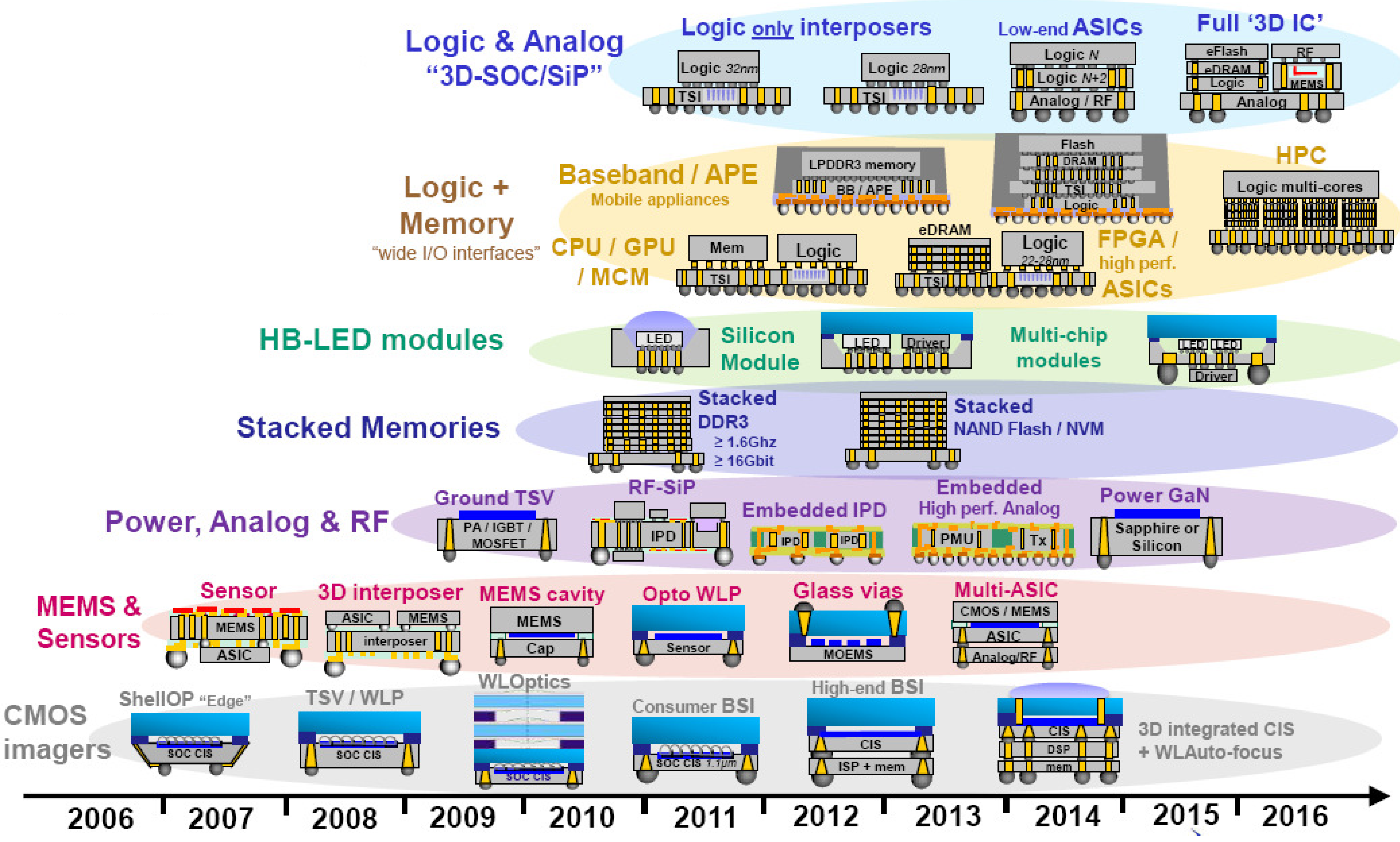
From Advanced Packaging to 3D Integration

- Technical and economical limitations increasingly slow down the shrink roadmap of integrated circuits
- Going into the third dimension by stacking chips allows for higher integrated devices and shifts the emphasis from size reduction and transistor improvements to advancements in interconnect performance.



- 3D integration promises greater space efficiency, lower power consumption and a significant increase in performance.
- SUSS MicroTec develops equipment and processes for 3D Integration

3D Integration: Chip Design Using the Third Dimension



Source: Yole Développement (2010)

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Strategic Restructuring Measures

Readjustments of Product Lines

- Sold loss making Test Systems division
- Acquired Hamatech APE
- Relocated the Substrate Bonder Division from the US to Germany

Consolidation of Production Sites

- From four at the beginning of 2010 to two by Q1, 2011
- Moved three product lines under one roof in Sternenfels
- Established Sternenfels as the main SUSS production site

Resizing of Field Offices to Meet Current and Future Business Requirements

- Closed Bangkok office
- Reduced size of the Japan office
- Increased Taiwan and China organizations
- Consolidated „Rest of Asia“ in Singapore
- Moved US sales and service organization to Silicon Valley

The Sternenfels Production Site

- Large production site (15.000 sqm) with two large clean rooms
  - Meets modern production and clean room standards
  - Supports anticipated expansion of business
- Three product lines centered under one roof
  - Photomask Equipment
  - Coater / Developer
  - Bonder
- Synergies within the development and production

Reduction of development and production sites from existing four in January 2010 to two highly efficient sites in Germany for the future

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Growth Opportunities – Short Term

Worldwide semiconductor revenue

- **2009 app. $228 billion**
- **2010 app. $300 billion (31.5% increase from 2009)**
- **2011 app. $314 billion (4.6% increase from 2010)**

Semiconductor Equipment Growth

	2010	**2011**	**2012**
Wafer Fab Equipment (mio$)	**28.032**	**29.116**	**33.227**
Growth (%)		**3,9**	**14,1**

	2010	**2011**	**2012**
Packaging & Assembly Equipment (mio$)	**6.050**	**6.424**	**6.647**
Growth (%)		**6,2**	**3,5**

(Source Gartner Sep. 2010)

> *“Certain equipment segments will have substantially higher growth. Demand for equipment for advanced processes, such as wafer-level packaging, 3D processes and TSV manufacturing, is expected to grow faster than the overall market”* (Gartner)

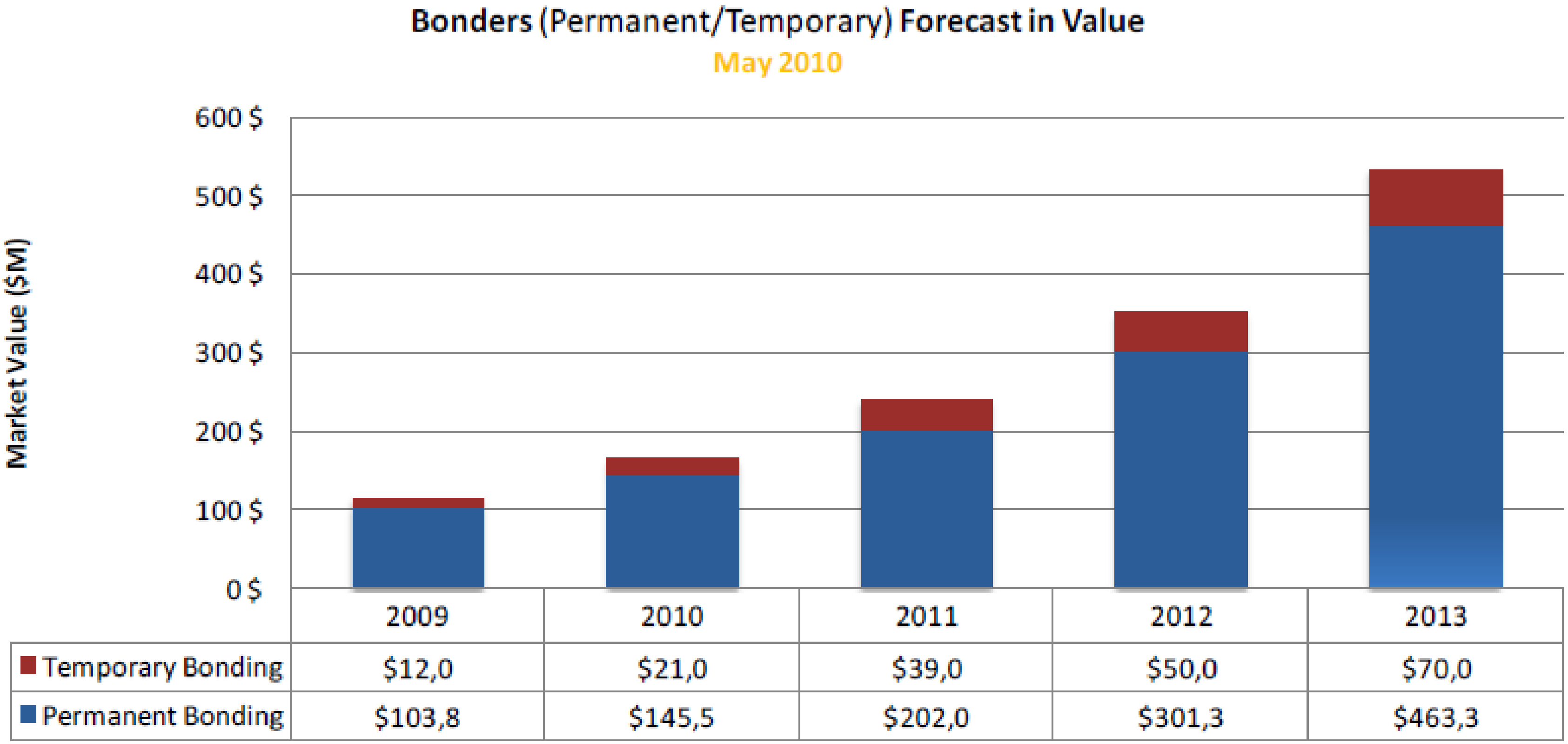
Growth Opportunities - Longterm

- The longterm growth perspective derives from the double digit growth rates of the target markets 3D Integration, Advanced Packaging, LED and MEMS
- Equipment purchases are mainly driven by
  - Capacity increases in established markets
    - Advanced Packaging, LED, MEMS
  - New technologies in emerging markets like 3D Integration
    - Thin wafer handling
    - permanent and temporary bonding of wafer stacks
    - TSV (Through Silicon Vias)
  - Leading edge process solutions for high volume front end manufacturing
    - Photomask cleaning solution for technology nodes 32nm and smaller

Growth Opportunities - Longterm

- Wafer bonding steps are increasingly yield and performance critical in the manufacturing of 3D Integration, LED and MEMS devices
- SUSS MicroTec is one of the leading supplier for substrate bonders in the semiconductor industry
  - 3D applications will lead to a sharp increase in permanent as well as temporary bonding applications
  - With the new modular XBC300 Bonder platform an extremely competitive cluster system was successfully introduced to the market
  - SUSS MicroTec is the only bonder equipment supplier that offers a variety of processes for “Thin Wafer Handling”
- The wafer bonder equipment market alone is estimated at 530 M$ in 2013 (Source: Yole, May 2010)
- SUSS MicroTec targets a market share of 30%+ which is in line with current numbers

The Wafer Bonder Equipment Market



Bonders (Permanent/Temporary) Forecast in Value

May 2010

	2009	2010	2011	2012	2013
🟥 Temporary Bonding	$12,0	$21,0	$39,0	$50,0	$70,0
🟦 Permanent Bonding	$103,8	$145,5	$202,0	$301,3	$463,3

- The Wafer Bonder Equipment Market is estimated at 530 M$ in 2013

Source: Yole Développement (May 2010)

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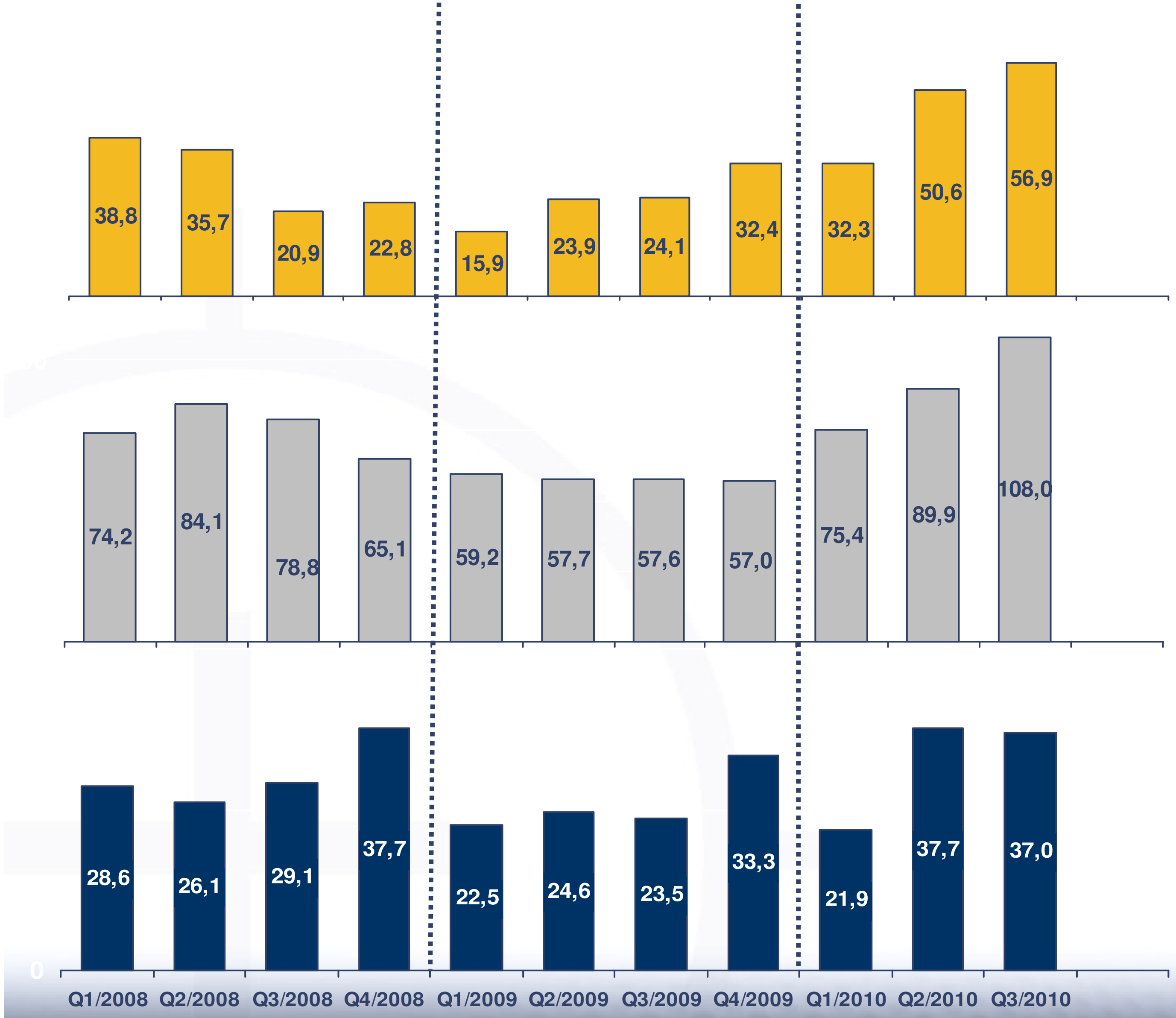
Key Financials 9M 2010

in € million	Q3 2010	Q3 2009	%	9M 2010	9M 2009	%
Order Entry	56.9	24.0	137.1	139.8	63.9	118.8
Order backlog as of 09/30	-	-	-	108.0	57.6	87.5
Sales	37.0	23.6	56.8	96.6	70.6	36.8
EBITDA	6.4	2.3	178.3	13.2	4.9	169.4
EBIT	5.0	1.1	>250.0	8.4	1.2	>250.0
Earnings after tax from continuing operations	2.5	0.8	212.5	3.6	0.5	>250.0
Earnings after tax from discontinued operations	0.6	(1.1)	145.5	0.0	(1.9)	100.0
Earnings after tax	3.1	(0.3)	>250.0	3.6	(1.4)	>250.0
Employees as of 09/30	-	-	-	587	487	20.5

33 Months Business Development



Order Entry

in € million

Order Backlog

in € milion

Sales

in € million

Segment Reporting 9M 2010

in € million	Lithography	Substrate Bonder	Photomask Equipment	Others	Total
Order Entry					
9M 2010	85.9	20.6	27.9	5.4	139.8
9M 2009	45.5	15.2	0.0	3.2	63.9
Sales					
9M 2010	65.7	19.0	7.1	4.8	96.6
9M 2009	52.9	14.2	0.0	3.5	70.6
Segment Result					
9M 2010	13.4	(5.7)	(0.2)	0.9	8.4
9M 2009	7.0	(1.8)	0.0	(4.0)	1.2
Employees					
09/30/2010	314	130	87	56	587
09/30/2009	314	118	0	55	487

SÜSS MicroTec

Cash Flow Statement 9M 2010

in € million	9M 2010	9M 2009
Net profit or loss	3.6	(1.4)
Cash Flow from operating activities	4.8	8.5
Cash Flow from investing activities	(21.2)	(8.0)
Free Cash Flow*	3.8	5.6
Cash Flow from financing activities	9.6	(4.8)
Cash and cash equivalents at the end of period	14.6	16.4
Net Cash**	23.5	15.3

* Before consideration of purchase or sale of available-for-sale securities and before consideration of extraordinary items from purchase or sale of securities

** incl. interest-bearing securities

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Outlook

Achievements	+ Strong competitive positioning: first or second in the target markets + Improved company structure for increased competitiveness and higher profitability + Solid financial situation
Outlook	+ Strong recovery of the semiconductor market + Target markets with double-digit growth rates within the coming five years + Strong growth potential for the Substrate Bonder in the medium term + Strategic alignment with industry and R&D partners
Guidance 2010	+ Order entry of app. € 190 million + Sales of app. € 140 million + EBIT between € 11 to 13 million despite one-off restructuring expenses of app. € 4.5 million + Positive Free Cash Flow

Thank you!